

Taiwan Semiconductor

# **Glass Passivated Bridge Rectifiers**

#### **FEATURES**

- Glass passivated junction
- Ideal for printed circuit board
- Reliable low cost construction
- UL Recognized File # E-326243
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC



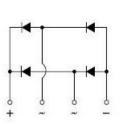




# **MECHANICAL DATA**

Case: KBL

Molding compound, UL flammability classification rating 94V-0 **Terminal:** Matte tin plated leads, solderable per JESD22-B102 Meet JESD 201 class 1A whisker test **Polarity:** Polarity as marked on the body **Weight:** 5.6 g (approximately)



PARAMETER	SYMBOL	KBL KBL		KBL	KBL	KBL	KBL	KBL	11-14
PARAMEIER		601G	602G	603G	604G	605G	606G	607G	Unit
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I <sub>F(AV)</sub>				6	-		-	Α
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load		175				А			
Rating for fusing (t<8.3ms)	l <sup>2</sup> t				127				A <sup>2</sup> s
Maximum instantaneous forward voltage (Note 1) $I_{\text{F}}\text{=}$ 3 A $I_{\text{F}}\text{=}$ 6 A	V <sub>F</sub>				1.0 1.1				v
Maximum DC reverse current $T_J=25 \degree C$ at rated DC blocking voltage $T_J=125\degree C$	۱ <sub>R</sub>	10 500				μA			
Typical thermal resistance	R <sub>θJL</sub> R <sub>θJA</sub>	7.5 13			°C/W				
Operating junction temperature range	TJ	- 55 to +150			°C				
Storage temperature range	T <sub>STG</sub>			-	55 to +15	50			°C

Note 1: Pulse Test with PW=300µs,1% Duty Cycle



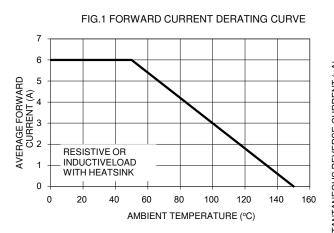
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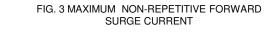
# **ORDERING INFORMATION**

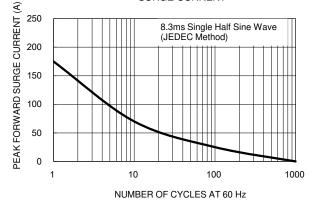
ORDERING CODE	PACKAGE	PACKING			
KBL601G T0	KBL	500 / Trays			
KBL602G T0	KBL	500 / Trays			
KBL603G T0	KBL	500 / Trays			
KBL604G T0	KBL	500 / Trays			
KBL605G T0	KBL	500 / Trays			
KBL606G T0	KBL	500 / Trays			
KBL607G T0	KBL	500 / Trays			

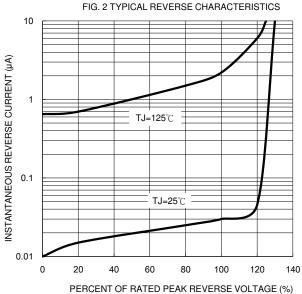
### **RATINGS AND CHARACTERISTICS CURVES**

(TA=25°C unless otherwise noted)

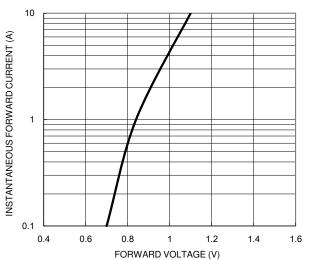






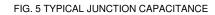


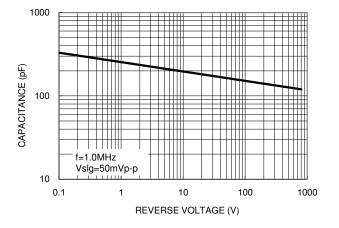
#### FIG. 4 TYPICAL FORWARD CHARACTERISTICS



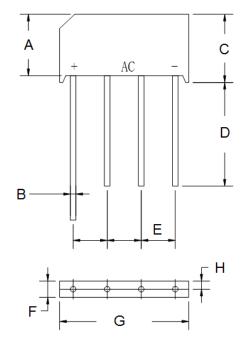


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#### **PACKAGE OUTLINE DIMENSIONS**



P/N

F

DIM.	Unit	(mm)	Unit (inch)		
DINI.	Min	Max	Min	Max	
Α	13.70	14.70	0.539	0.579	
В	1.20	1.30	0.047	0.051	
С	15.20	16.30	0.598	0.642	
D	19.00	-	0.748	-	
E	4.60	5.60	0.181	0.220	
F	5.50	6.50	0.217	0.256	
G	18.50	19.50	0.728	0.768	
Н	2.1 (TYP)		0.083 (TYP)		

#### **MARKING DIAGRAM**



- = Specific Device Code
- YWW = Date Code
  - = Factory Code



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